(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
17 November 2005 (17.11.2005)

PCT

(10) International Publication Number
WO 2005/109492 A1

(51) International Patent Classification[7]: H01L 21/78

(21) International Application Number:
PCT/KR2004/003127

(22) International Filing Date:
30 November 2004 (30.11.2004)

(25) Filing Language: Korean

(26) Publication Language: English

(30) Priority Data:
10-2004-0032326 7 May 2004 (07.05.2004) KR

(71) Applicant *(for all designated States except US)*: **HANMI SEMICONDUCTOR CO., LTD** [KR/KR]; #532-2, Kajwa-Dong, Seo-Ku, Incheon 404-250 (KR).

(72) Inventors: **NA, Ik-Kyun**; 202-1506, Jugong Apt., 29bunji, Mansu 4-dong, Namdong-gu, Incheon 403-854 (KR). **KIM, Suk-Bae**; 105-1103, Hankuk Apt. Bugae 1-dong, Bupyeong-gu, Incheon 403-101 (KR). **CHOI, Seung-Hee**; 101-104, Jugong Apt. 564-1bunji, Nonhyeon-dong, Namdong-gu, Incheon 405-850 (KR).

(74) Agent: **OH, Wi-Hwan**; 5th Fl, Eunseong Bldg., 601-18, Yeoksam-Dong, Kangnam-Gu, Seoul 135-080 (KR).

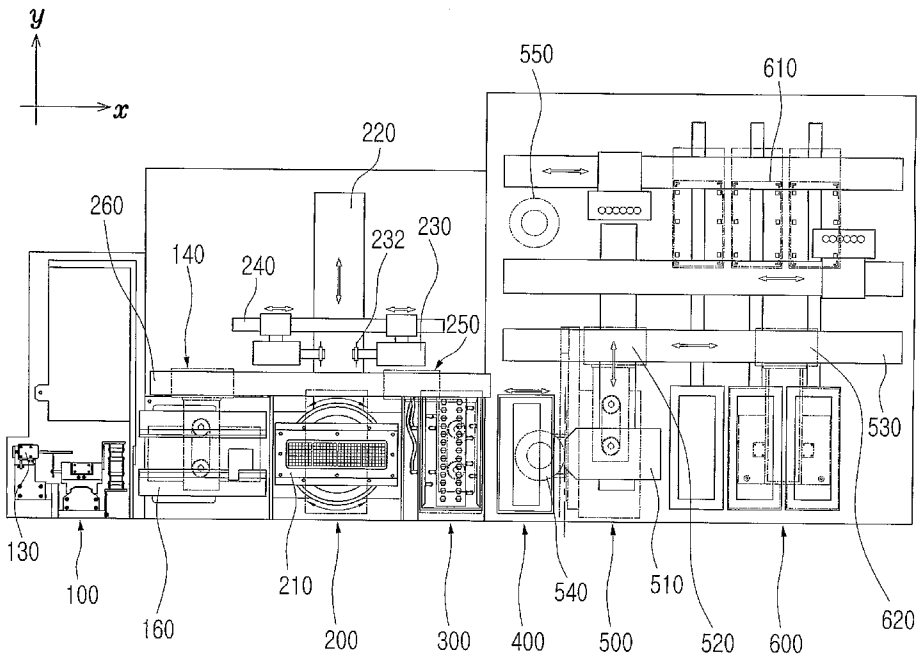
(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: SAWING AND HANDLER SYSTEM FOR MANUFACTURING SEMICONDUCTOR PACKAGE



(57) Abstract: Disclosed is a sawing and handler system for manufacturing a semiconductor package. The system includes an on-loader unit, a sawing machine and a cleaning unit, which are sequentially aligned in the system so that the semiconductor strip or the semiconductor package sequentially passes through the on-loader unit, the sawing machine and the cleaning unit according to a process order thereof, thereby improving the sawing and processing speed of the system for the semiconductor strip.

WO 2005/109492 A1